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(54) SEMICONDUCTOR DEVICE, MANUFACTURE THEREOF, AND LEAD FRAME APPLIED THERETO

(57)Abstract:

PURPOSE: To obtain a semiconductor device small in size and large in heat dissipating capacity by a method wherein the outer sections of heat dissipating fins protruding from the side face of a resin-sealed package are bent and arranged so as to overlap each other in a top view.

CONSTITUTION: A tab 7 to which a semiconductor pellet 15 is bonded, leads 6 electrically connected to the semiconductor pellet 15, and heat dissipating fins 8 linked to the tab 7 are provided. A package 20 which seals up the tab 7, the pellet 15, and part of the leads 6 and the leads 6 with resin is provided. The outer parts 9 of the heat dissipating fins 8 extending from the side of the resin-sealed package 20 are bent and arranged so as to overlap each other in a top view above the resin-sealed package 20. By this setup, a semiconductor device of this design enhanced in heat dissipating area, small in size as a whole, and large in heat dissipating capacity can be obtained.

